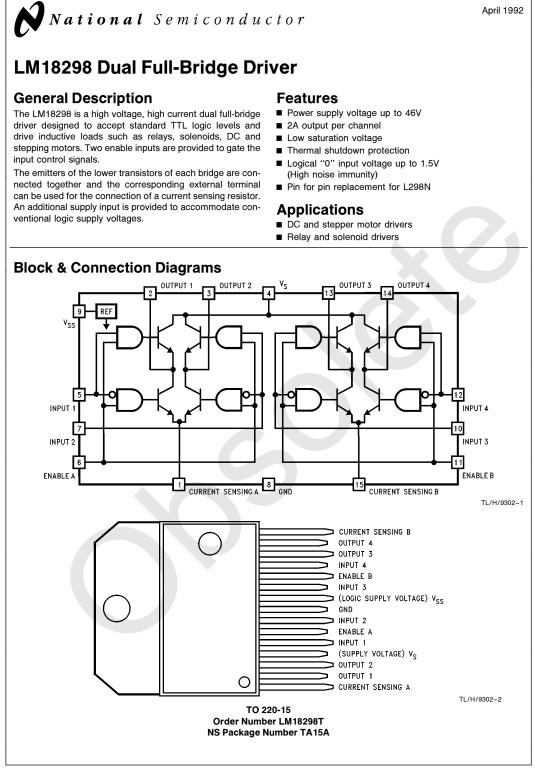
LM18298

LM18298 Dual Full-Bridge Driver



Literature Number: SNOSC18A



© 1995 National Semiconductor Corporation TL/H/9302

RRD-B30M115/Printed in U. S. A.

_M18298 Dual Full-Bridge Driver

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distribut Main Supply (Pir

Office/Distributors for availability and spe Main Supply (Pin 4) Logic Supply (Pin 9)	cifications. 50V 7V	ESD Susceptibility Lead Temperatur Storage Tempera
Logic Inputs (Pins 5, 6, 7, 10, 11, 12)	-0.3 to 7V	Operating
Peak Output Current (Per Channel) Non-Repetitive (t = 100 μs) Repetitive (80% duty cycle, t _{ON} = 10 ms)	3A 2.5A	Junction Tempera Main Supply (Pin

2A

Sense Voltage (Pins 1, 15)	-1 to +2.3V
Power Dissipation (Note 2)	25W
ESD Susceptibility (Note 3)	1 kV
Lead Temperature (Soldering, 10 second	ds) 260°C
Storage Temperature Range	-65° C to $+150^{\circ}$ C

Ratings

rature Range (T_J) -40°C to +150°C Main Supply (Pin 4)

46V

Electrical Characteristics

DC Operation

 V_S = 42V, V_{SS} = 5V, I_O = 0A, T_J = 25°C, L = 0V, H = 5V, unless otherwise specified

Symbol	Parameter	Conditions	Typical (Note 4)	Limit (Note 5)	Units (Limits)
VS	Main Supply Voltage (Pin 4)			V _{SS} + 2.5	V (min)
				46	V (max)
V _{SS}	Logic Supply Voltage (Pin 9)			4.5	V (min)
				7	V (max)
IS Main Supply Quiescent Current	Enable = H, Input = L	9	22		
	(Pin 4)	Enable = H, Input = H	32	70	mA (max
		Enable = L, Input = X		4	
I _{SS}	Logic Supply Quiescent Current	Enable = H, Input = L	22	36	
(Pin 9)	Enable = H, Input = H	6	12	mA (max	
		Enable = L, Input = X		6	
V _{IL} Low Level Input Voltage (Pins 5, 7, 10, 12)	Low Level Input Voltage			-0.3	V (min)
	(Pins 5, 7, 10, 12)			1.5	V (max)
V _{IH}	High Level Input Voltage			2.3	V (min)
(Pin	(Pins 5, 7, 10, 12)			V _{SS}	V (max)
IIL	Low Level Input Current (Pins 5, 7, 10, 12)	Input = L		-10	μA (max
IIH	High Level Input Current (Pins 5, 7, 10, 12)	Input = H	30	100	μA (max
V _{EN L} Low Level Enable Voltage (Pins 6, 11)			-0.3	V (min)	
	(Pins 6, 11)			1.5	V (max)
V _{EN H} High Level Enable Voltage (Pins 6, 11)				2.3	V (min)
			V _{SS}	V (max)	
I _{EN L}	Low Level Enable Input Current (Pins 6, 11)	Enable = L		-10	μA (max
I _{EN H}	High Level Enable Input Current (Pins 6, 11)	Enable = H	30	100	μA (max

Symbol	Parameter	Conditions	Typical (Note 4)	Limit (Note 5)	Units (Limits)
02 000 (11)	Source Saturation Voltage	I _O = 1A	1.35	1.7	V (max)
	(Pins 2, 3, 13, 14)	$I_0 = 2A$	2.0	2.7	
V _{CE sat (L)} Sink Saturation Voltage (Pins 2, 3, 13, 14)	Sink Saturation Voltage	I _O = 1A	1.2	1.6	V (max)
	(Pins 2, 3, 13, 14)	$I_{O} = 2A$	1.7	2.3	
V _{CE sat} Total Drop		I ₀ = 1A		3.2	V (max
V _{CE sat (H)} + V _{CE sat (L)}	V _{CE sat (H)} + V _{CE sat (L)}	$I_{O} = 2A$		4.9	V (max
V _{sense} Sensing Voltage (Pins 1, 15)		$t \le 50 \ \mu s$		-1	V (min)
		Continuous		-0.5	• ()
		Continuous		2	V (max)
T ₁	Source Current Turn-Off Delay	0.5 Input to 0.9 I _O (<i>Figure 2</i>)	0.5		μs
T ₂	Source Current Fall Time	0.9 I _O to 0.1 I _O (<i>Figure 2</i>)	0.15		μs
T ₃	Source Current Turn-On Delay	0.5 Input to 0.1 I _O (<i>Figure 2</i>)	1.3		μs
Т4	Source Current Rise Time	0.1 I _O to 0.9 I _O (<i>Figure 2</i>)	0.85		μs
T ₅	Sink Current Turn-Off Delay	0.5 Input to 0.9 I _O (<i>Figure 3</i>)	0.25		μs
т ₆	Sink Current Fall Time	0.9 I _O to 0.1 I _O (<i>Figure 3</i>)	0.1		μs
T ₇	Sink Current Turn-On Delay	0.5 Input to 0.1 I _O (<i>Figure 3</i>)	1.3		μs
T ₈	Sink Current Rise Time	0.1 I _O to 0.9 I _O (<i>Figure 3</i>)	0.1		μs
f _C	Commutation Frequency	$I_0 = 2A$	25		kHz

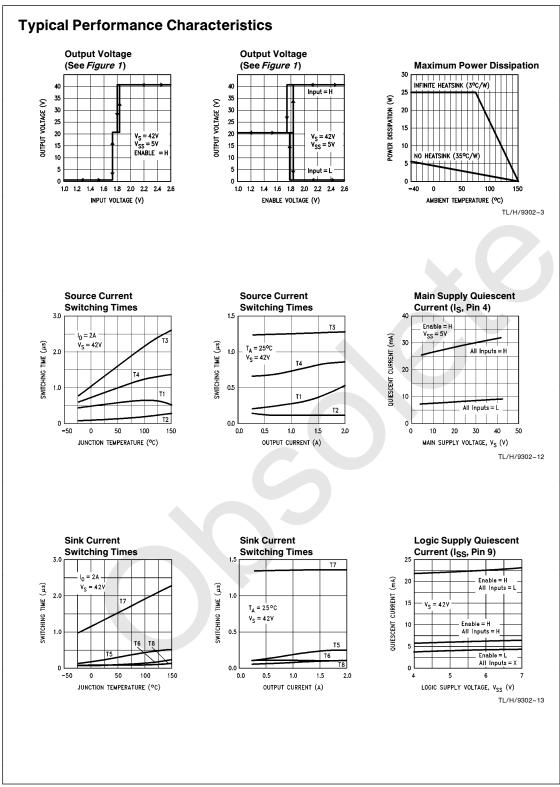
Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified Operating Ratings.

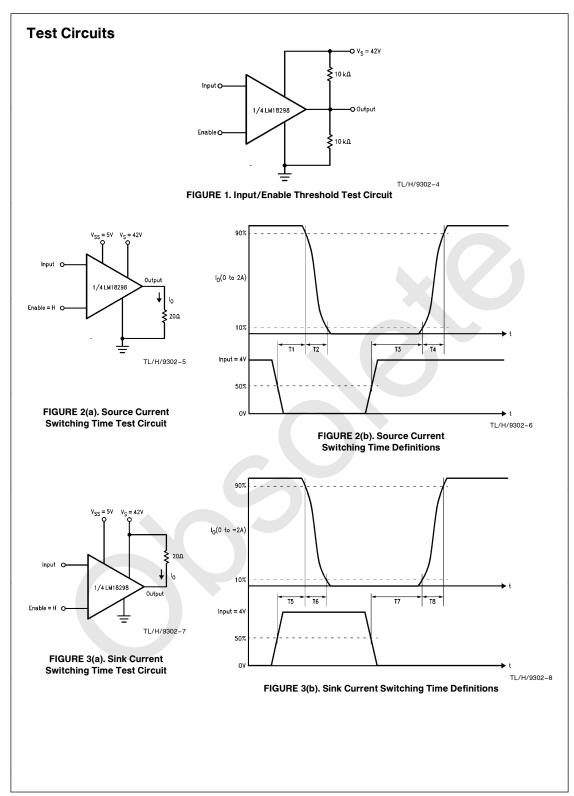
Note 2: The maximum power dissipation must be derated at elevated temperatures and is a function of $T_{J max}$. θ_{JC_i} and T_C . The maximum allowable power dissipation at any temperature is $P_{D max} = (T_{J max} - T_C)/\theta_{JC}$ or the number given in the **Absolute Maximum Ratings**, whichever is lower. The typical junction-to-case thermal resistance (θ_{JC}) of the LM18298 is 3°C/W.

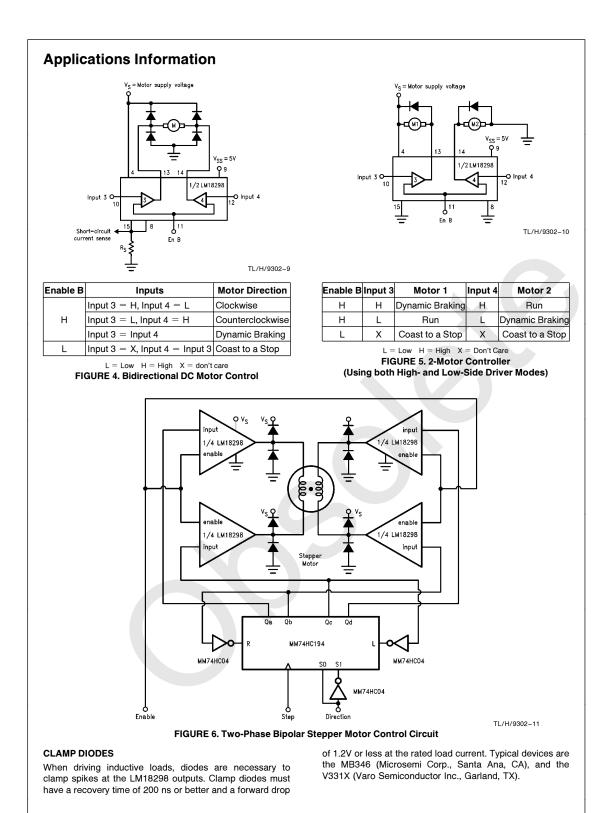
Note 3: Human body model, 100 pF discharged through a 1.5 k Ω resistor.

Note 4: Typicals are at 25°C and represent the most likely parametric norm.

Note 5: Limits are guaranteed and 100% tested.

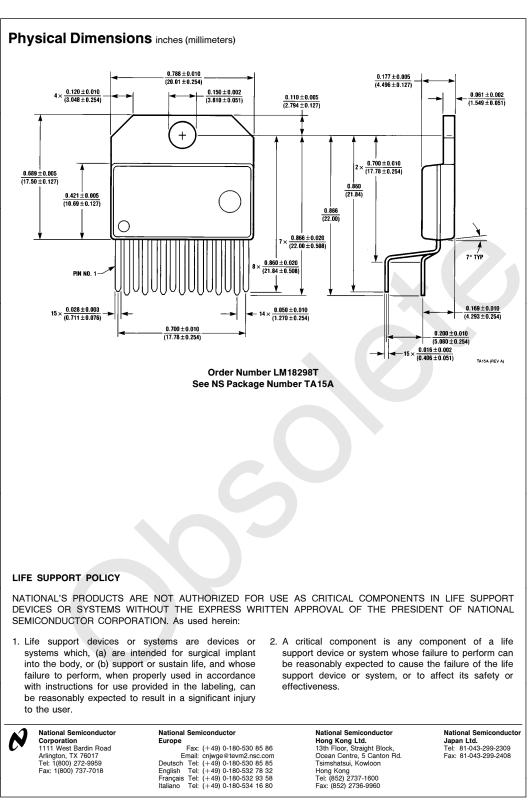












National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

	Products		Applications	
	Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
	Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
	Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
	DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
	DSP	dsp.ti.com	Industrial	www.ti.com/industrial
	Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
	Interface	interface.ti.com	Security	www.ti.com/security
	Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
	Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
	Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
	RFID	www.ti-rfid.com		
	OMAP Mobile Processors	www.ti.com/omap		
	Wireless Connectivity	www.ti.com/wirelessconnectivity		
			u Hama Dawa	a O a Al a a m

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated